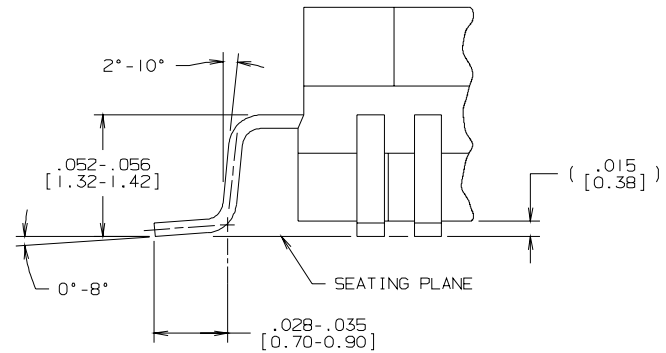
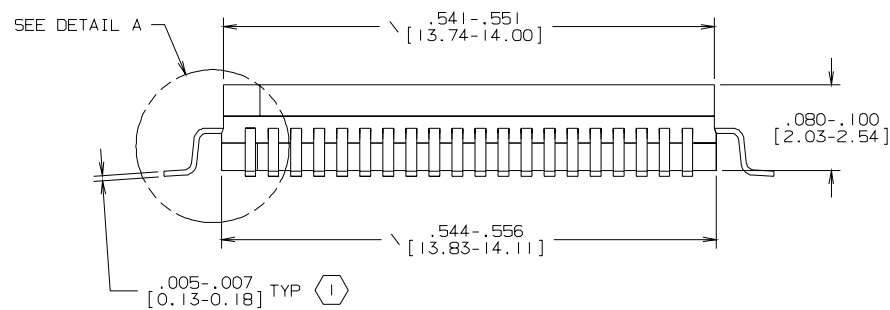
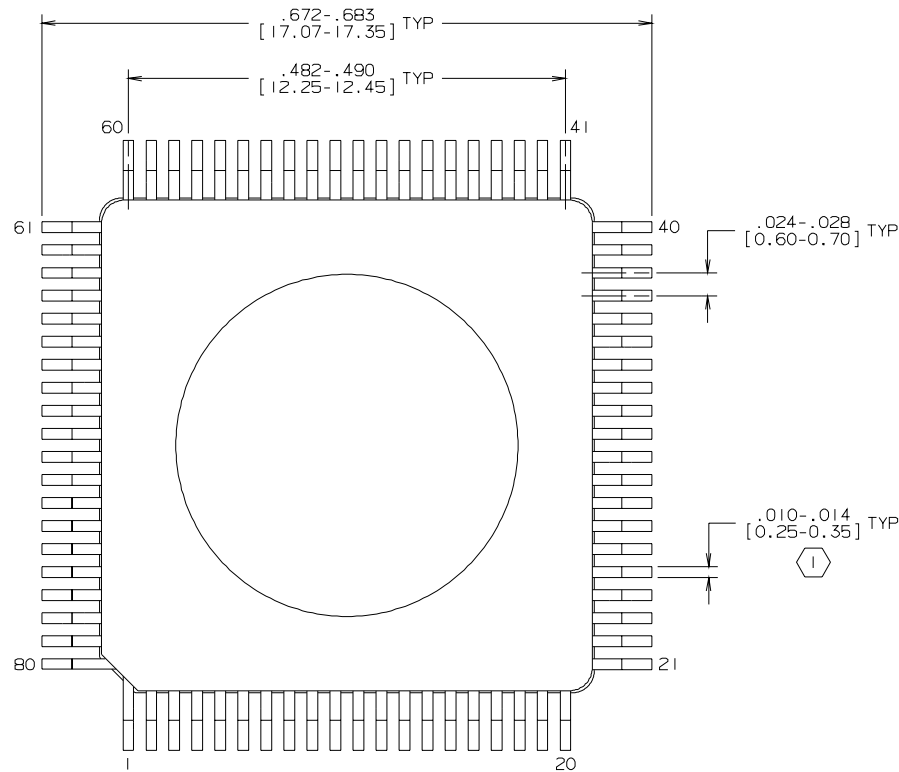


R E V I S I O N S				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	09071	03/24/92	MS/



DETAIL A
TYPICAL

NOTES: UNLESS OTHERWISE SPECIFIED

1. LEADFRAME TO BE TIN PLATED TO 300 MICROINCHES/ 7.62 MICROMETERS MINIMUM OVER BASE METAL. MAXIMUM THICKNESS INCLUDES LEAD FINISH.

CONTROLLING DIMENSION: MILLIMETER				
APPROVALS	DATE	 NATIONAL SEMICONDUCTOR CORPORATION 2900 Semiconductor Drive, Santa Clara, CA 95052-8090		
DRAWN	MARTA SUCHY			
DFTG. CHK.				
ENGR. CHK.				
APPROVAL		CERQUAD, EIAJ, 80 LEAD, EPROM		
PROJECTION		SCALE	SIZE	DRAWING NUMBER
 INCH [MM]		N/A	C	MKT-WA80AQ
		DO NOT SCALE DRAWING		SHEET 1 OF 1